

SOT1308-1

Plastic thermal enhanced very thin small outline package; no leads; 16 terminals

10 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON16
Package type industry code	HVSON16
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-7-2011

Table 1. Package summary

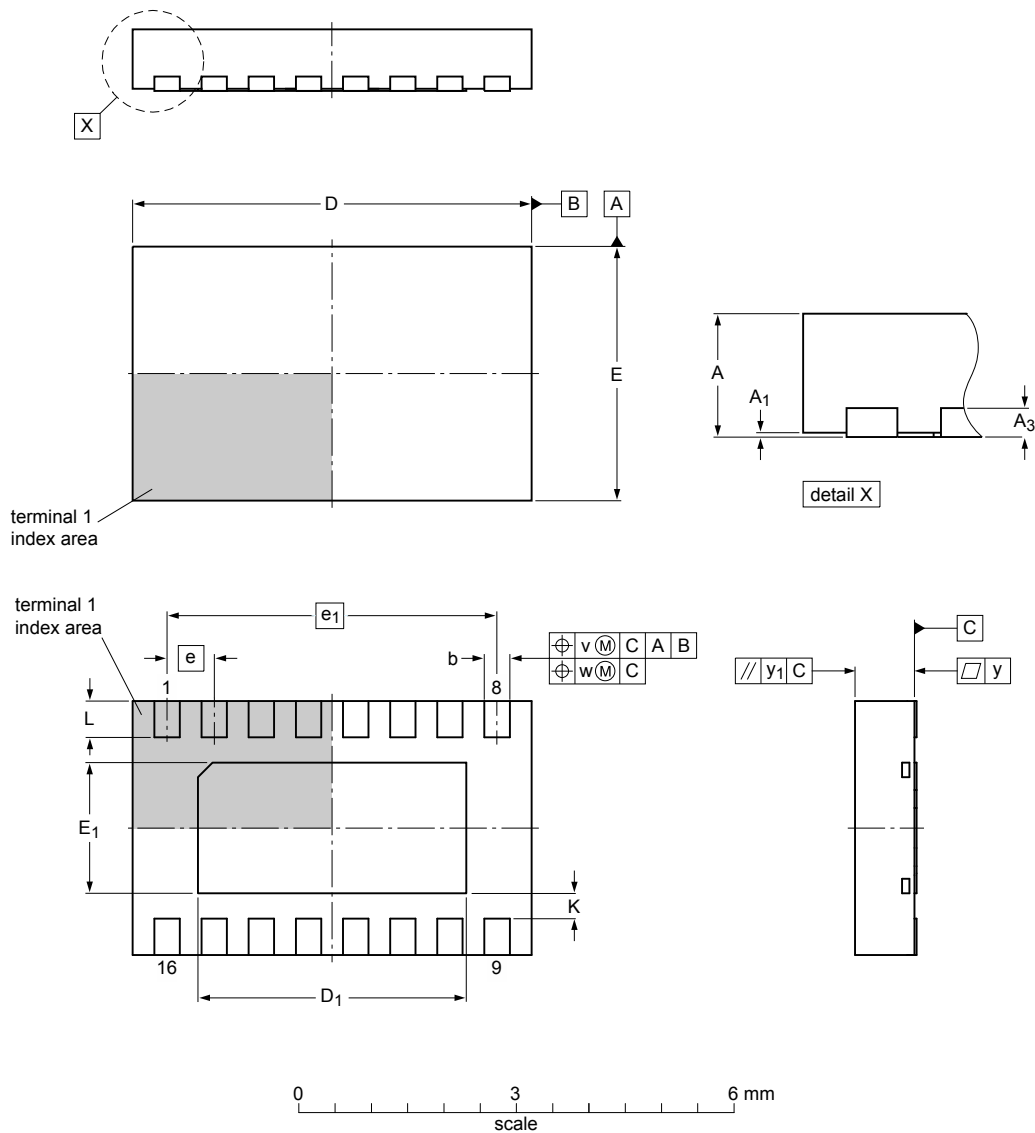
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

HVSON16: plastic thermal enhanced very thin small outline package; no leads; 16 terminals; body 3.5 x 5.5 x 0.85 mm

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Dimensions

Unit	A	A ₁	A ₃	b	D	D ₁	E	E ₁	e	e ₁	k	L	v	w	y	y ₁
max	1.00	0.05		0.35	5.6	3.75	3.6	1.85				0.55				
nom	0.85		0.2	0.32	5.5	3.70	3.5	1.80	0.65	4.55		0.50	0.1	0.05	0.05	0.1
min	0.80	0.00		0.29	5.4	3.65	3.4	1.75			0.2	0.45				

sot1308-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1308-1		MO-229			-11-07-04- 11-11-25

Fig. 1. Package outline HVSON16 (SOT1308-1)

3. Soldering

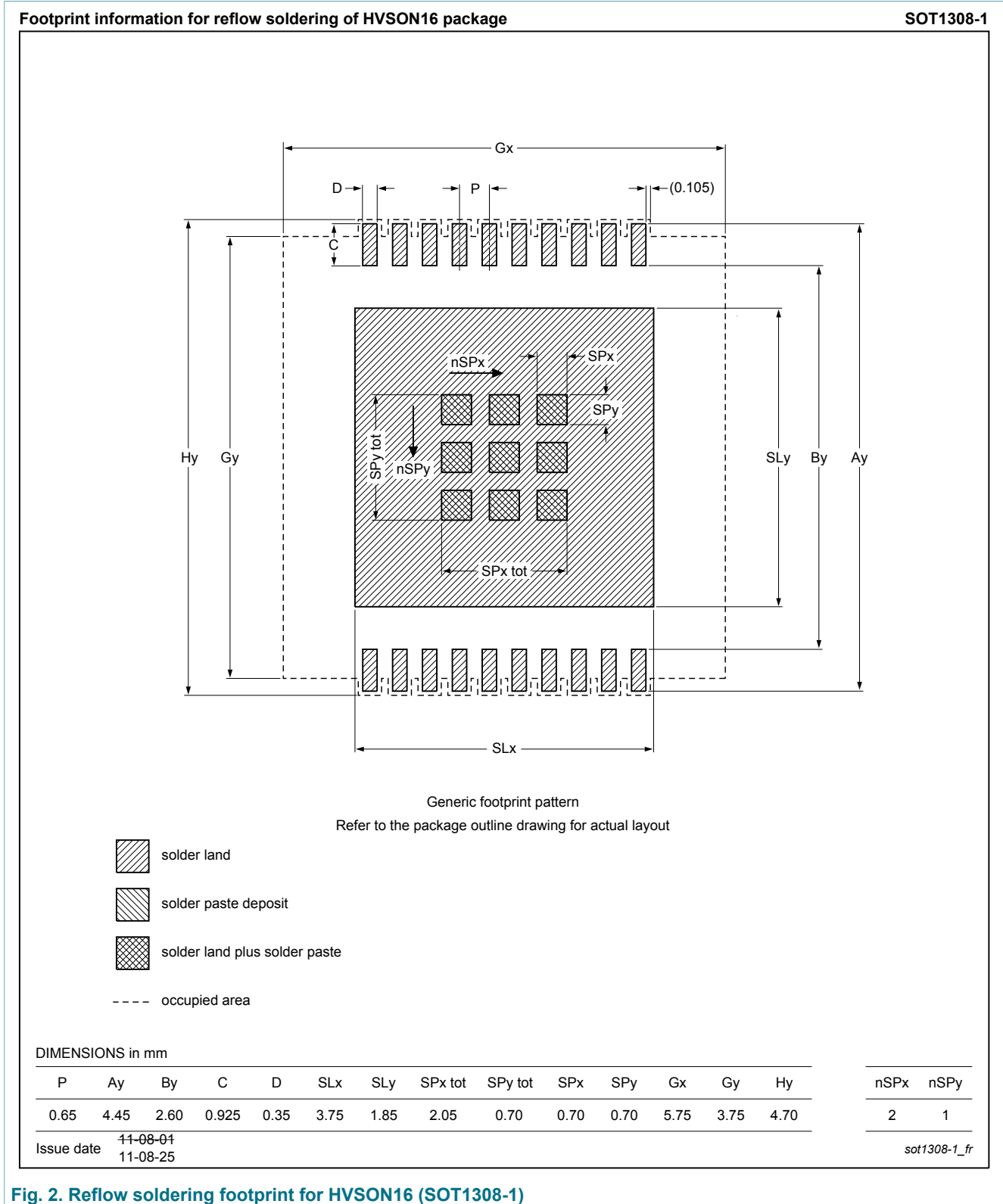


Fig. 2. Reflow soldering footprint for HVSON16 (SOT1308-1)

4. Legal information

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